




REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
		PRELIMINARY		

NOTES:

1. DIMENSIONS: MM
2. BUMP MATERIAL: 95 Pb / 5 Sn
3. LASER MARK INDICATING END OF PACKAGE CONTAINING BUMP ROW A
4. BULK SILICON EXPOSED ON FOUR SIDES AND TOP
5. UNDERFILL REQUIRED FOR RELIABILITY OF SOLDER JOINT ON FR4 SUSTRATE
6. RECOMMENDED SUBSTRATE LAND PATTERN (NSMD PADS): LAND PAD ϕ 0.23; SOLDER MASK APERTURE ϕ 0.33.
7. SUGGESTED ASSEMBLY SOLDER PASTE APERTURE: ϕ 0.30.
8. ELECTRICAL NODES -- SEE PRODUCT DEVICE DATA SHEET OR PROBE DOCUMENT

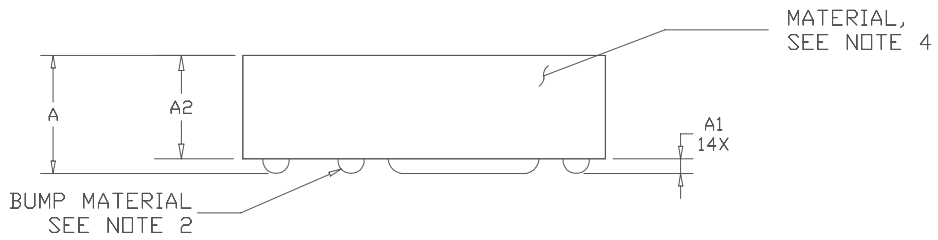
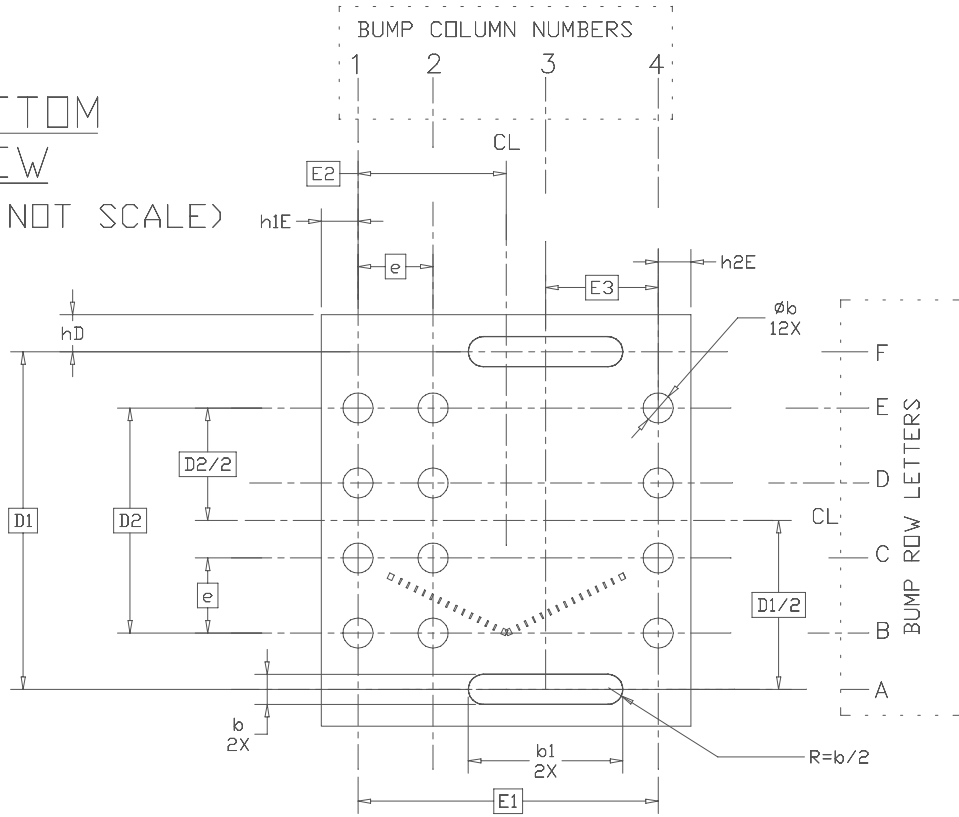
TABLE -- MECHANICAL DIMENSIONS				
SYMBOL	MIN.	NOM.	MAX.	NOTE
A	0.67	--	0.92	
A1	0.075	0.100	0.127	
A2	0.60	--	0.793	6" OR 8" WAFER
D		2.69		BSC
D1		2.25		BSC
D2		1.50		BSC
hD		0.20		BSC
E		2.52		BSC
E1		2.00		BSC
E2		0.94		BSC
E3		0.75		BSC
h1E		0.31		BSC
h2E		0.21		BSC
e		0.50		BSC
b	0.19	0.20	0.24	
b1	0.99	1.03	1.07	

SIGNATURE	DATE	 Dallas Semiconductor MARKETING OUTLINE - DS2762X FLIP CHIP PACKAGE			
QA APVD:					
ENGR MGR:					
ENGR BY:					
CHECK BY:		SIZE A	FSCM NO.	DWG NO. 56-G2762-001	REV A
DRAWN BY:		SCALE NONE		SHEET 1 / 2	

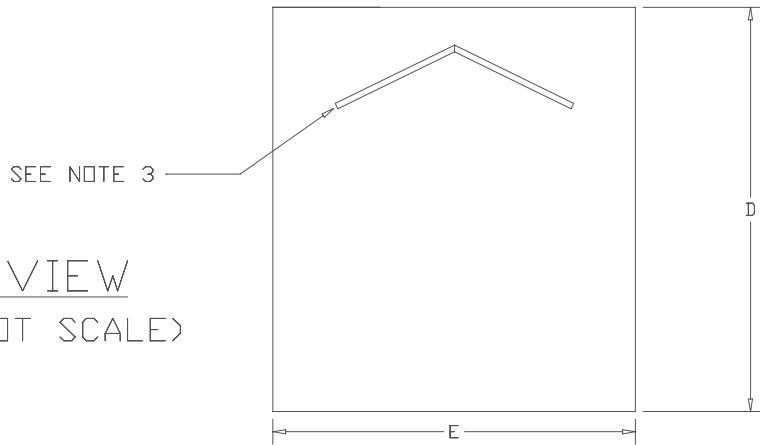


BOTTOM
VIEW

<DO NOT SCALE>



TOP VIEW
<DO NOT SCALE>



SIZE A	FSCM NO.	DWG NO. 56-G2762-001	REV A
SCALE NONE	SHEET 2 / 2		